

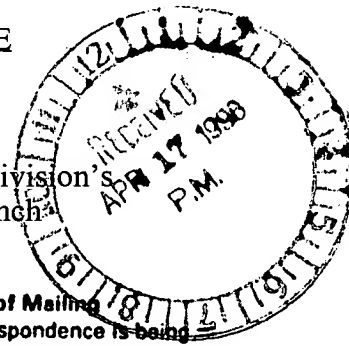
17C1

80A 2601-CIP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
KENICHI NAKAMURA
Serial No. 08/884,778
Filed: June 30, 1997
For: BIODEGRADABLE MOLDING MATERIAL

Application Processing Division
Customer Correction Branch



Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents and Trademarks, Washington, D.C. 20231 on 12-11-97

LETTER

Hon. Commissioner of Patents and Trademarks
Washington, D.C. 20231

Dear Sir:

WILLIAM L. ANDROLIA
(date of deposit)
Typed or printed name of person signing this certificate
Signature Dated

Upon receipt of Filing Receipt issued in connection with the above-identified application, a few omissions were noted. In particular and as indicated in the enclosed marked-up copy of the Filing Receipt, the FIL FEE REC'D section should be --\$395.00-- instead of "0". The TOT CL and IND CL sections should be --2-- and --1--, respectively, and not "0". The Applicant(s) section should include --,TAKARAZUKA, JAPAN-- after "KENICHI NAKAMURA" and the Filing Receipt should indicate that this application is of Small Entity status. A copy of a complete communication sent in response to the Notice to File Missing Parts of Application, which was enclosed with the above-mentioned Filing Receipt as received by the Patent Office, is enclosed for your further information and which will clarify matters.

It is therefore respectfully requested that the Patent Office issue a corrected Filing Receipt indicating the above changes accordingly.

RECEIVED

APR 28 1998

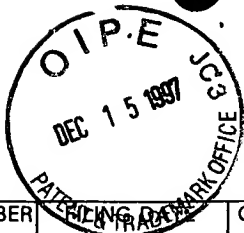
GROUP 2100

Respectfully submitted,
KODA AND ANDROLIA

10100 Santa Monica Boulevard
Suite 2340
Los Angeles, CA 90067
(310) 277-1391

By: [Signature]
William L. Androlia
Reg. No. 27,177

FILING RECEIPT



UNITED STATES DEPARTMENT OF COMMERCE
Patent and Trademark Office
ASSISTANT SECRETARY AND COMMISSIONER
OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTORNEY DOCKET NO.	DRWGS	TOT CL	IND CL
08/884,778	06/30/97		\$0.00	200246 IP	1	0	0

* 385.⁰⁰ DEC 05 1997

KODA AND ANDROLIA
10100 SANTA MONICA BLVD
SUITE 2340
LOS ANGELES CA 90067

KODA & ANDROLIA

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Application Processing Division's Customer Correction Branch within 10 days of receipt. Please provide a copy of the Filing Receipt with the changes noted thereon.

Applicant(s)

KENICHI NAKAMURA, *TAKARAZUKA, JAPAN*

CONTINUING DATA AS CLAIMED BY APPLICANT-

THIS APPLN IS A CIP OF 08/770,087 12/19/96 ABN

FOREIGN/PCT APPLICATIONS-JAPAN
JAPAN

8-78400
9-152828

03/05/96
05/26/97

FOREIGN FILING LICENSE GRANTED 11/28/97

TITLE

BIODEGRADABLE MOLDING MATERIAL

SMALL ENTITY

PRELIMINARY CLASS:



80A 2601-CIP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

COPY

In re Application of:)
KENICHI NAKAMURA)
Serial No. 08/884,778)
Filed: June 30, 1997)
For: BIODEGRADABLE MOLDING)
MATERIAL)

Group Art Unit: 1108

Examiner: Michael Marcheschi

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Commissioner for Patents and Trademarks, Washington, D.C. 20231 on 10-27-97

(date of deposit)

WILLIAM L. ANDROLIA

LETTER
RE

Typed or printed name of person signing this certificate

Signature

Dated 10-27-97

LATE FILING OF DECLARATION

Hon. Commissioner of Patents and Trademarks
Washington, D.C. 20231

Dear Sir:

With regard to the above-identified application, enclosed herewith please find:

1. A Declaration and Power of Attorney signed by the Inventor and a check in the amount of \$65.00 to cover the late filing fee;
2. An Assignment signed by the Inventor and a Recordation Form Cover Sheet along with a check for \$40.00 to cover the Assignment recordation fees;
3. An English translation of the non-English specification (the processing fee of \$130.00 was paid along with the application of June 30, 1997); and
4. A verified U.S. format English specification.

Please charge any additional costs incurred by or in order to implement this Letter to Koda and Androlia Deposit Account No. 11-1445.

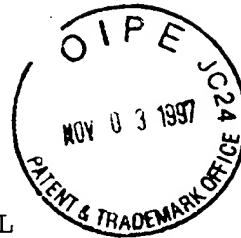
Respectfully submitted,

KODA AND ANDROLIA

By:

William L. Androlia
Reg. No. 27,177

10100 Santa Monica Blvd.
Suite 2340
Los Angeles, CA 90067



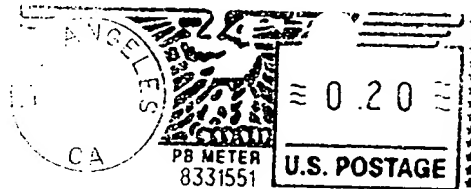
80A 2601-CIP FUJITA
Inventor: KENICHI NAKAMURA
Serial No. 08/884,178
For: BIODEGRADABLE MOLDING MATERIAL

LETTER WITH MAILING CERTIFICATE, DECLARATION & PWR
OF ATTY, ASSIGNMENT, RECORDATION COVER SHEET,
ENGLISH TRANSLATION OF NON-ENGLISH SPECIFICATION
WITH VERIFICATION, AND VERIFIED U.S. PATENT
SPECIFICATION AND CHECKS FOR \$65.00 AND \$40.00.

NOV 18 1997

Sent to PO: October 27, 1997

KODA & ANDROLIA



LAW OFFICES OF
KODA & ANDROLIA
10100 SANTA MONICA BLVD., SUITE 2340
LOS ANGELES, CALIFORNIA 90067



- ___ 9. Amend the specification by inserting after "filed _____",
--now abandoned--.
- ___ 10. Transfer the drawings from the prior application to this application and abandon said prior application as of the filing date accorded this application.
- X 11. The power of attorney in the prior application is to H. Henry Koda, Reg. No. 27,729;
William L. Androlia, Reg. No. 27,177, et al.
- (a) The power appears in the original papers of the prior application.
- (b) Address all future communication to:
- KODA AND ANDROLIA
10100 Santa Monica Boulevard
Suite 2340
Los Angeles, California 90067
- X 12. Declaration & Power of Attorney, Assignment and Small Entity forms will follow.
- X 13. CIP Application is enclosed (in Japanese).
- ___ 14. The certified copy(s) upon which priority is claimed are contained in Serial No. _____, filed _____.
- X 15. Convention priority is claimed based upon Japanese Patent Applications No. 8-78400 of March 5, 1996 and No. 9-152828 of May 26, 1997.
- ___ 16. Please enter the Rule 116 Amendment from the pending prior application.
- X 17. Verified Statement Claiming Small Entity Status is contained in Serial No. 08/770,087,
filed December 19, 1996.
- X 18. A check in the amount of \$130.00 to cover the processing of an application
filed with a specification in a non-English language is enclosed.

Respectfully submitted,

KODA AND ANDROLIA

By: _____
William L. Androlia
Reg. No. 27,177

___ Inventor(s)

___ Assignee of
Complete Interest

X Attorney/Agent of
Record in Prior
Application

Dated: June 30, 1997

10100 Santa Monica Boulevard
Suite 2340
Los Angeles, CA 90067
Tel: (310) 277-1391
Fax: (310) 277-4118

COPY

DECLARATION AND POWER OF ATTORNEY

PATENT (U.S.A.)
KODA & ANDROLIA
ATTORNEY'S DOCKET NO.

80A-2601-CIP.....

As a below named inventor, I declare that :

My residence, post office address and citizenship are stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

BIODEGRADABLE MOLDING MATERIAL

attached hereto unless the following box is checked:

☒ was filed on 06/30/97 as United States Application Number or PCT International Application Number 08/884,778

and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or Inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the appropriate line, any foreign application for patent or Inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed.

PRIOR FOREIGN APPLICATION(S)						
COUNTRY	APPLICATION NUMBER	DATE OF FILING			PRIORITY CLAIMED	
		Month	Day	Year		
Japan	8-78400	03	05	1996	YES <input checked="" type="checkbox"/>	NO _____
Japan	9-152828	05	26	1997	YES <input checked="" type="checkbox"/>	NO _____
					YES _____	NO _____
					YES _____	NO _____

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below.

APPLICATION NUMBER	FILING DATE

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

APPLICATION NUMBER	FILING DATE	STATUS - PATENTED, PENDING, ABANDONED

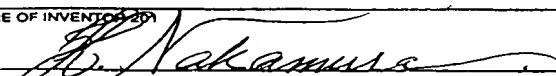
POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) to prosecute this application and transact all business in the Patent and Trademark Office connected herewith.

WILLIAM L. ANDROLIA, REG. NO. 27,177; H. HENRY KODA, Reg. No. 27,729; ALEX CHARTOVE, Reg. No. 31,942.

SEND ALL CORRESPONDENCE TO: KODA & ANDROLIA 10100 SANTA MONICA BLVD., SUITE 2340 LOS ANGELES, CALIFORNIA 90067	DIRECT TELEPHONE CALLS TO: KODA & ANDROLIA (310) 277-1391
--	--

21	Name of Inventor	FIRST NAME KENICHI	LAST NAME NAKAMURA	MIDDLE NAME	Residence CITY TAKARAZUKA	STATE or COUNTRY CA
	Post Office Address 22-33, Hiraisanso, Takarazuka-shi, Hyogo, Japan					
						CITIZENSHIP Japan
22	Name of Inventor	FIRST NAME	LAST NAME	MIDDLE NAME	Residence CITY	STATE or COUNTRY
	Post Office Address					
						CITIZENSHIP
23	Name of Inventor	FIRST NAME	LAST NAME	MIDDLE NAME	Residence CITY	STATE or COUNTRY
	Post Office Address					
						CITIZENSHIP
24	Name of Inventor	FIRST NAME	LAST NAME	MIDDLE NAME	Residence CITY	STATE or COUNTRY
	Post Office Address					
						CITIZENSHIP

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements and the like may jeopardize the validity of the application or any patent issued thereon.

SIGNATURE OF INVENTOR 201 	SIGNATURE OF INVENTOR 202
DATE October 20, 1997	DATE
SIGNATURE OF INVENTOR 203	SIGNATURE OF INVENTOR 204
DATE	DATE

☐ Additional inventors are named on separate Declarations attached hereto.

RECORDATION FORM COVER SHEET
PATENTS ONLY

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office
80A 2601-CIP

Tab settings □ □ □ ▼

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

KENICHI NAKAMURA

Name and address of receiving party(ies)

Name: INDUSTRIAL TECHNICAL R & D
LABORATORY, INC.

Internal Address: _____

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other _____

Street Address: 22-33, Hiraisanso,

Takarazuka-shi, Hyogo, Japan

City: _____ State: _____ ZIP: _____

Execution Date: October 20, 1997

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

08/884,778

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: KODA AND ANDROLIA

Internal Address: _____

Street Address: 10100 Santa Monica Blvd.,
Suite 2340

City: Los Angeles State: CA ZIP: 90067

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

11-1445

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William L. Androlia
Reg. No. 27,177

Name of Person Signing

Signature

10-27-1997

Date

Total number of pages including cover sheet, attachments, and document: 2

Assignment

80A 2601-CIP

COPY

(1) KENICHI NAKAMURA

(2) _____

(3) _____ and

(4) _____

(1-4) Insert Name(s) of
Inventor(s)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign and hereby does assign, transfer and set over to

(5) Insert name of Assignee

(5) INDUSTRIAL TECHNICAL R & D LABORATORY, INC.

(6) Insert address of Assignee

(6) of 22-33, Hiraisanso, Takarazuka-shi,
Hyogo, Japan

(hereinafter designated as the Assignee) the entire right, title and interest for the United States, its territories, dependencies and possessions, in the invention known as

(7) Insert Title of Invention

(7) BIODEGRADABLE MOLDING MATERIAL

for which the undersigned has (have) executed an application for patent in the United States of America

(8) Insert Date of Signing of
Application(8) on October 20, 1997

1) The undersigned agree(s) to execute all papers necessary in connection with the application and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

6) The undersigned hereby grant(s) WILLIAM L. ANDROLIA, Reg. No. 27,177 and H. HENRY KODA, Reg. No. 27,729, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

Date 10-20-1997 Signature of Inventor K. Nakamura (SEAL)

Date _____ Signature of Inventor _____ (SEAL)

Date _____ Signature of Inventor _____ (SEAL)

Date _____ Signature of Inventor _____ (SEAL)

This assignment should preferably be signed before: (a) a Notary Public if within the U.S.A. (b) a U.S. Consul if outside the U.S.A. If neither, then it should be signed before at least two witnesses who also sign here:

Date _____ Witness _____

Date _____ Witness _____

KODA & ANDROLIA
USA

SMALL BUSINESS

Attorney's

Applicant or Patentee: Kenichi Nakamura

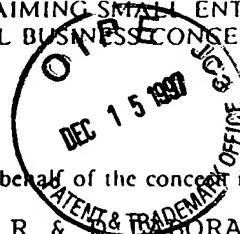
Serial or Patent No.: _____

Docket No.: 80A 2601

Filed or Issued: _____

For: BIODEGRADABLE MOLDING MATERIAL

VERIFIED STATEMENT (DECLARATION) CLAIMING SMALL ENTITY
STATUS (37 CFR 1.9 (f) and 1.27 (c)) — SMALL BUSINESS CONCERN



COPY

I hereby declare that I am

☐ the owner of the small business concern identified below:

☒ an official of the small business concern empowered to act on behalf of the concern identified below:

NAME OF CONCERN INDUSTRIAL TECHNICAL R & LABORATORY, INC.

ADDRESS OF CONCERN 22-33, Hiraisanso, Takarazuka-shi,
Hyogo, Japan

I hereby declare that the above identified small business concern qualifies as a small business concern as defined in 13 CFR 121.3-18, and reproduced in 37 CFR 1.9 (d), for purposes of paying reduced fees under section 41(a) and (b) of Title 35, United States Code, in that the number of employees of the concern, including those of its affiliates, does not exceed 500 persons. For purposes of this statement, (1) the number of employees of the business concern is the average over the previous fiscal year of the concern of the persons employed on a full-time, part-time or temporary basis during each of the pay periods of the fiscal year, and (2) concerns are affiliates of each other when either, directly or indirectly, one concern controls or has the power to control the other, or a third party or parties controls or has the power to control both.

I hereby declare that rights under contract or law have been conveyed to and remain with the small business concern identified above with regard to the invention, entitled BIODEGRADABLE MOLDING MATERIAL

KENICHI NAKAMURA

by inventor(s)
described in

☒ the specification filed herewith

☐ application serial no. _____, filed _____

☐ patent no. _____, issued _____

If the rights held by the above identified small business concern are not exclusive, each individual, concern or organization having rights to the invention is listed below* and no rights to the invention are held by any person, other than the inventor, who could not qualify as a small business concern under 37 CFR 1.9 (d) or by any concern which would not qualify as a small business concern under 37 CFR 1.9 (d) or a nonprofit organization under 37 CFR 1.9 (e).

*NOTE: Separate verified statements are required from each named person, concern or organization having rights to the invention averring to their status as small entities. (37 CFR 1.27)

NAME _____

ADDRESS _____

☐ INDIVIDUAL

☐ SMALL BUSINESS CONCERN

☐ NONPROFIT ORGANIZATION

NAME _____

ADDRESS _____

☐ INDIVIDUAL

☐ SMALL BUSINESS CONCERN

☐ NONPROFIT ORGANIZATION

I acknowledge the duty to file, in this application or patent, notification of any change in status resulting in loss of entitlement to small entity status prior to paying, or at the time of paying, the earliest of the issue fee or any maintenance fee due after the date on which status as a small entity is no longer appropriate. (37 CFR 1.28 (b))

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this verified statement is directed.

NAME OF PERSON SIGNING Kenichi Nakamura

TITLE OF PERSON OTHER THAN OWNER President

ADDRESS OF PERSON SIGNING 22-33, Hiraisanso, Takarazuka-shi,
Hyogo, Japan

SIGNATURE Kenichi Nakamura

DATE 25 October 1996